

DLC-uRWELL Detector R&D Progress from USTC

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The 11th Workshop on Hadron Physics in China and
Opportunities Worldwide

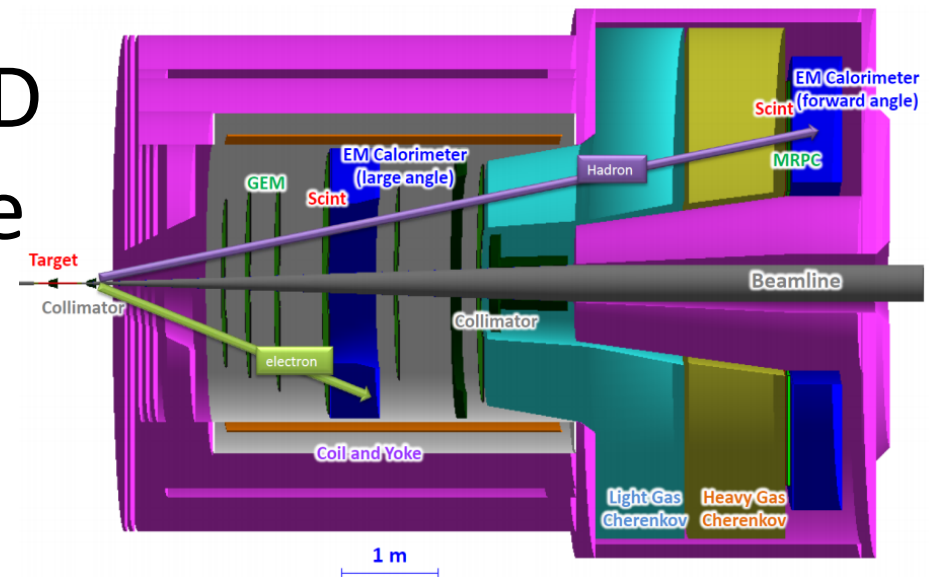
Nankai University, Tianjin, China
August 26, 2019

Outline

- Introduction
- DLC coating
- uRWELL with 2d readout
- High-rate uRWELL
- VMM readout
- Summary

Introduction

- GEM is the baseline option of the tracker for the SoLID experiment.
 - High rate capability
 - Good spatial resolution
 - Large area and low mass
- uRWELL as a novel MPGD is a promising alternative to GEM as a detector option for the SoLID tracker



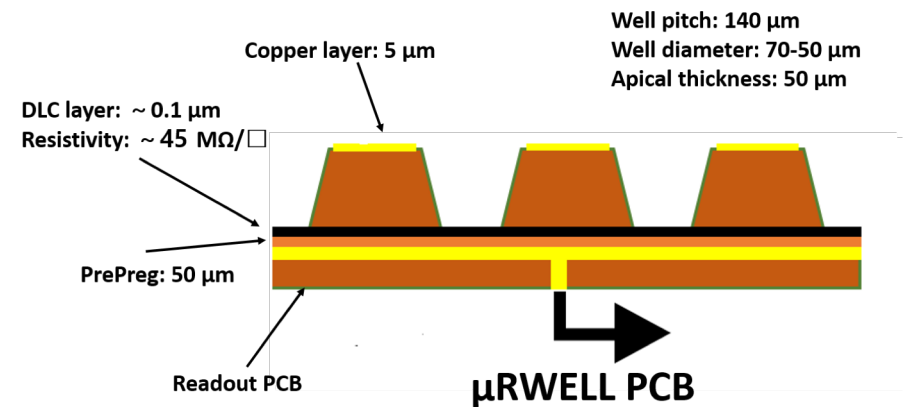
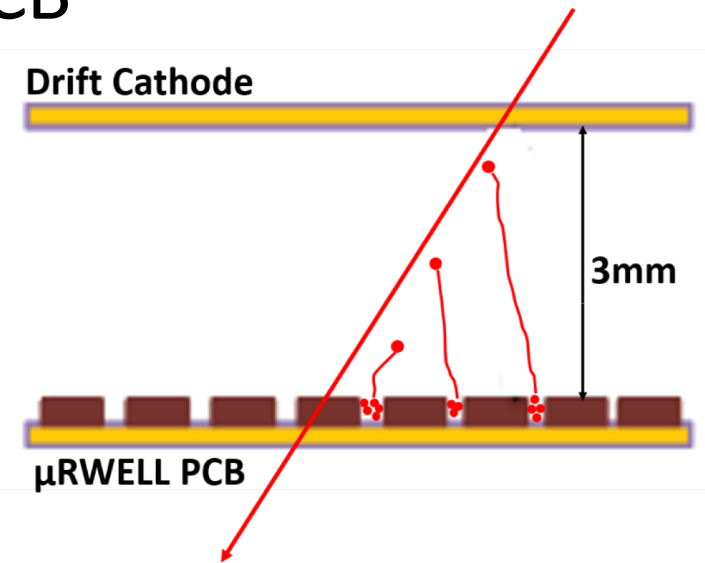
uRWELL: Micro-Resistive WELL

- uRWELL = Drift board + uRWELL PCB

- simple and compact structure
- low mass and good gain uniformity
- no gluing, no spacers, no stretching, no rigid frames
- fast assembling
- cost effective

- uRWELL PCB = A stack of “readout PCB / insulating pre-preg / resistive DLC / well-type holes”

- DLC is a critical component

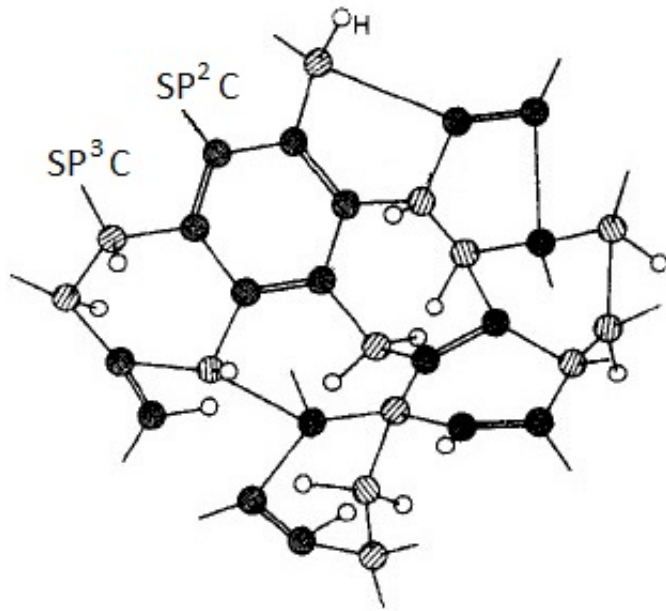


Well pitch: 140 μm
Well diameter: 70-50 μm
Apical thickness: 50 μm

Spark-protected single well-type amplification stage

DLC: Diamond-Like Carbon

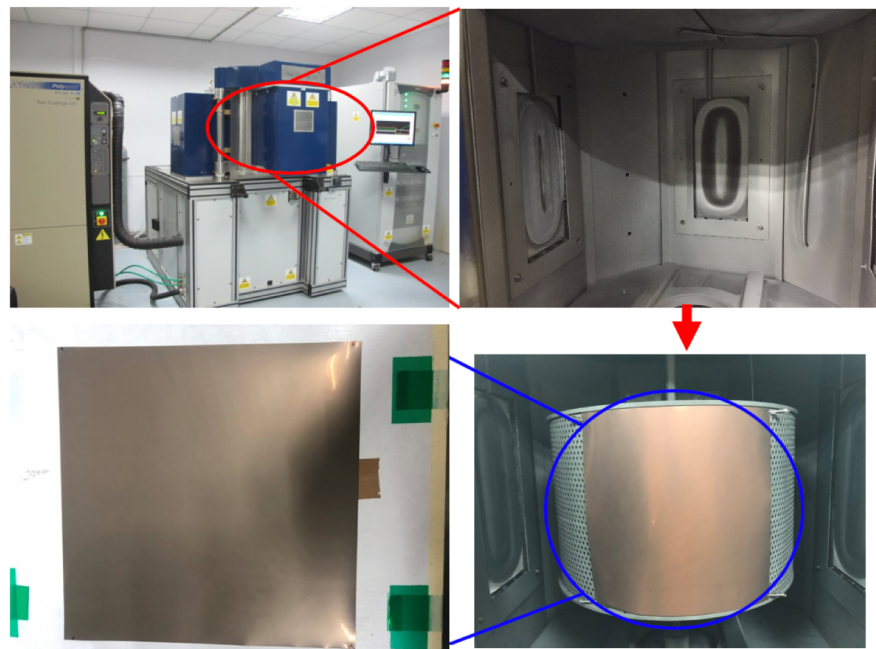
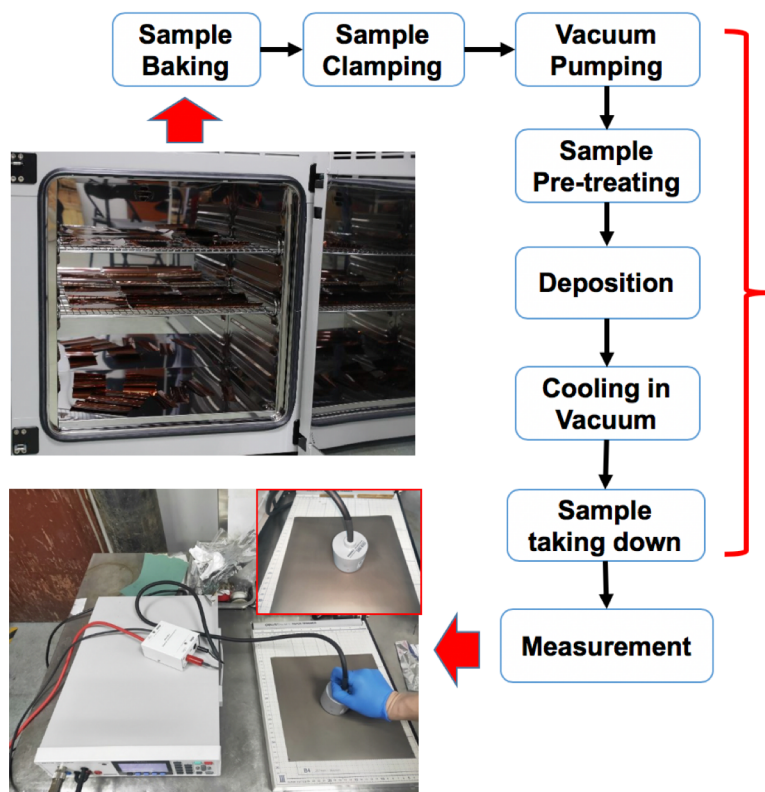
- DLC: metastable amorphous carbon material containing both diamond-structure and graphite-structure
- A new big star rapidly rising in the MPGD field
 - resistive electrodes by DLC coating



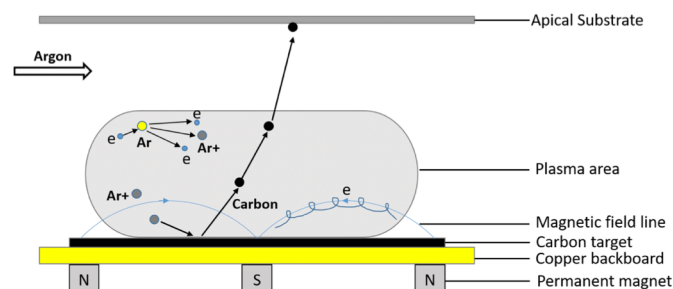
- ✓ *Stable surface resistivity which can be precisely adjusted*
- ✓ *Robust and stable both chemically and physically*
- ✓ *Sub-micrometer level coating for fine resistive structures*
- ✓ *Precise pattern can be made by using photolithography*
- ✓ *Available for large area*

DLC with Magnetron Sputtering

Depositing DLC on a substrate with magnetron sputtering technique to form a high-quality resistive electrode



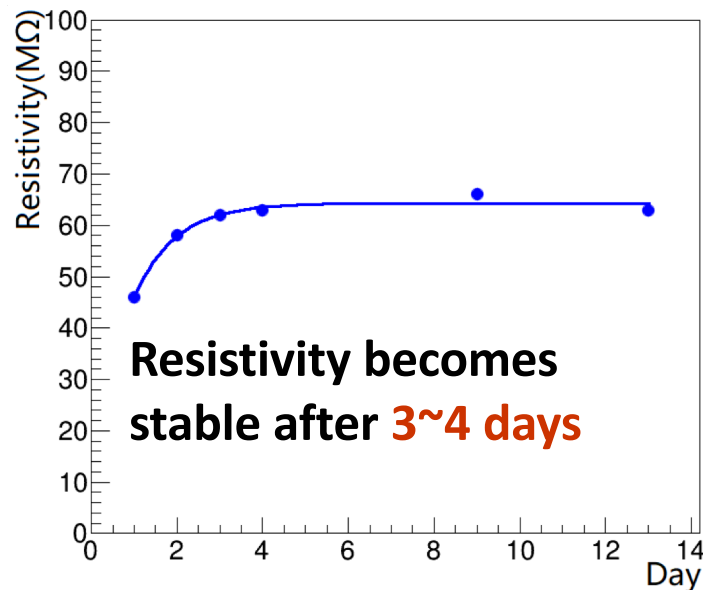
Magnetron sputtering technique



In close collaboration with State Key Laboratory of Solid Lubrication, Lanzhou Institute of Chemical Physics

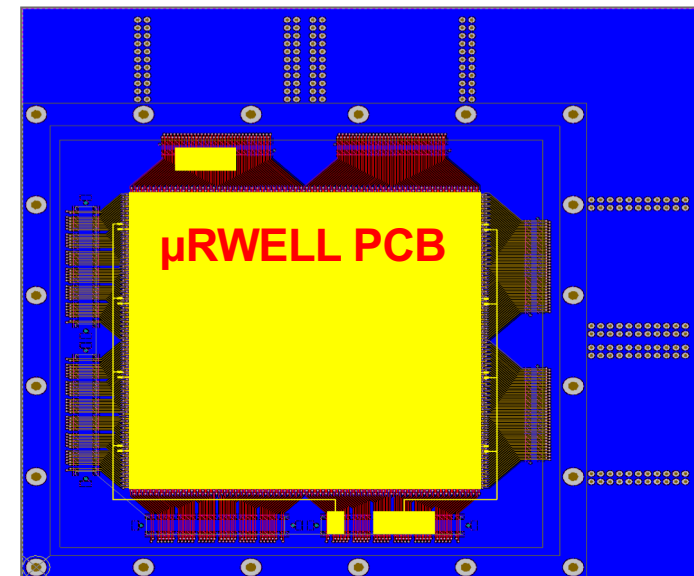
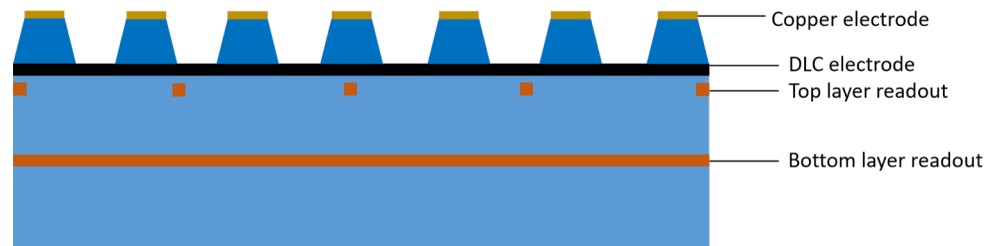
DLC Resistive Electrode Samples

- Thickness from tens to hundreds nanometers
- A large range in surface resistivity available: $1\text{M}\Omega/\square \sim 500\text{M}\Omega/\square$, which can be controlled by adjusting target power, deposition time, vacuum degree and doping.
- Good resistivity uniformity achieved

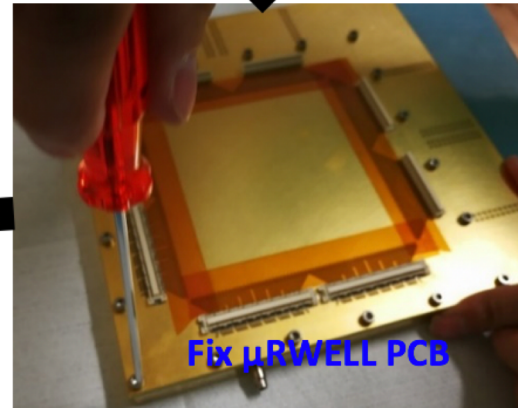
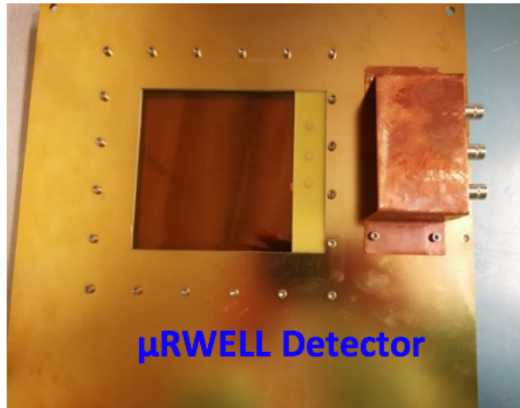
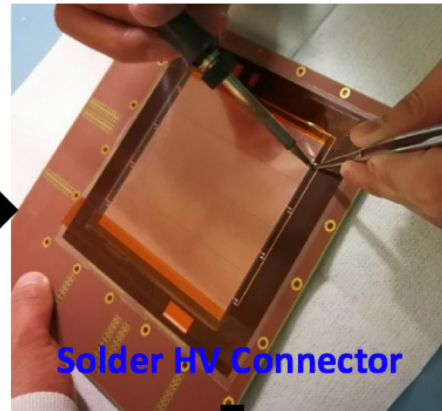
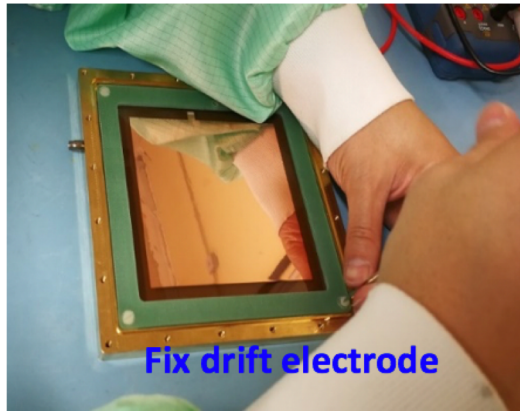


Design of a 2D μ RWELL PCB

- 2 layers of readout strips in orthogonal configuration for 2-D position measurement
- An active area of 10cm*10cm into 4 sectors
- Strip pitch: 400 μ m
- Larger strips at bottom to compensate weaker signals induced at bottom strips



Detector Fabrication



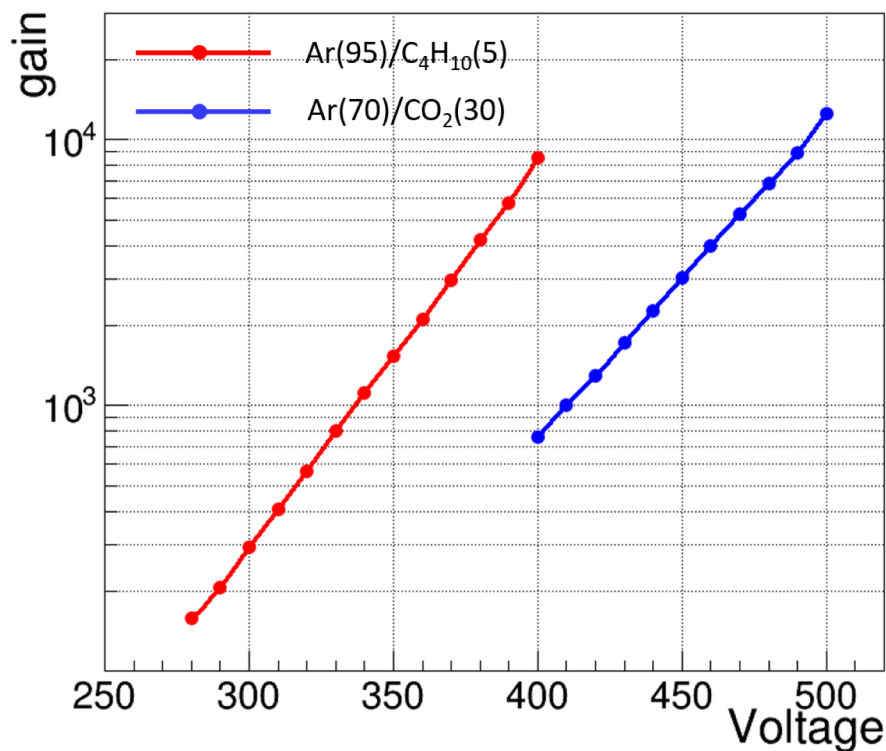
- Drift electrode: 50 μ m APICAL foil coated with copper
- DLC Electrode resistivity: 40M Ω
- Active area : 10cm \times 10cm
- Drift gap : 3 mm
- 4 Hirose connector + 4 Panasonic connector

A 2D μ RWELL detector with Chinese DLC !

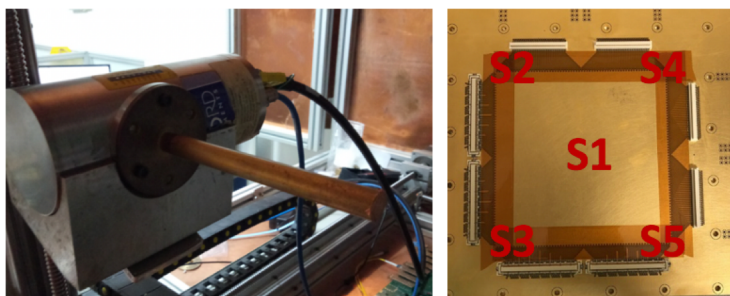
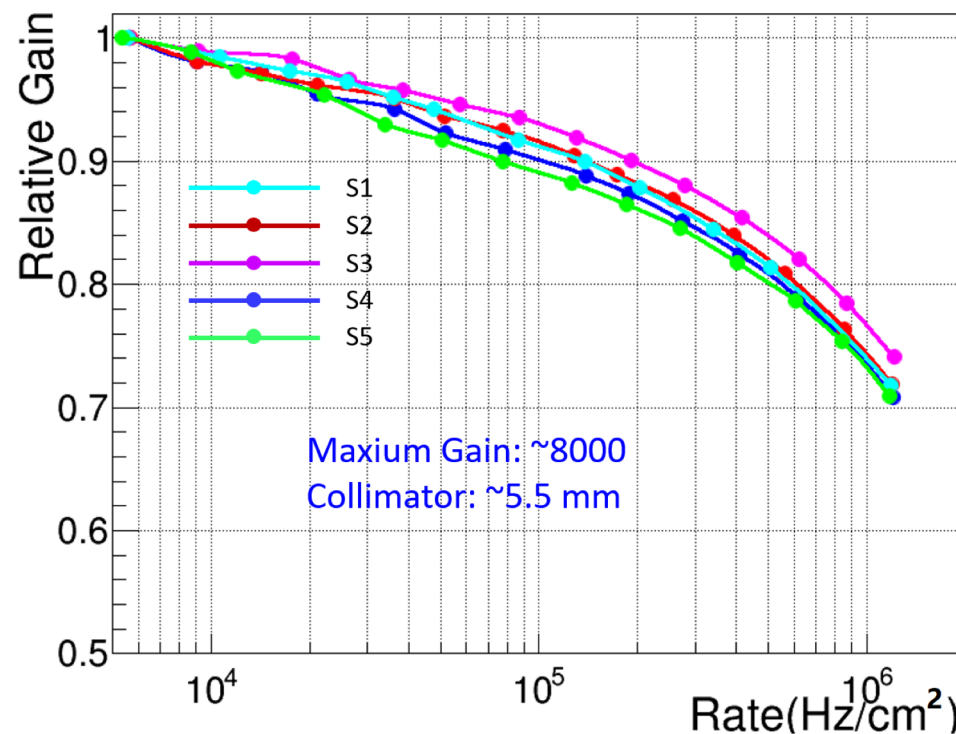
Special thanks to Antonio Teixeira and Rui De Oliveira for technical help.

Gas Gain and Rate Capability

Gas gain can reach 10^4 , very high for single stage amplification.

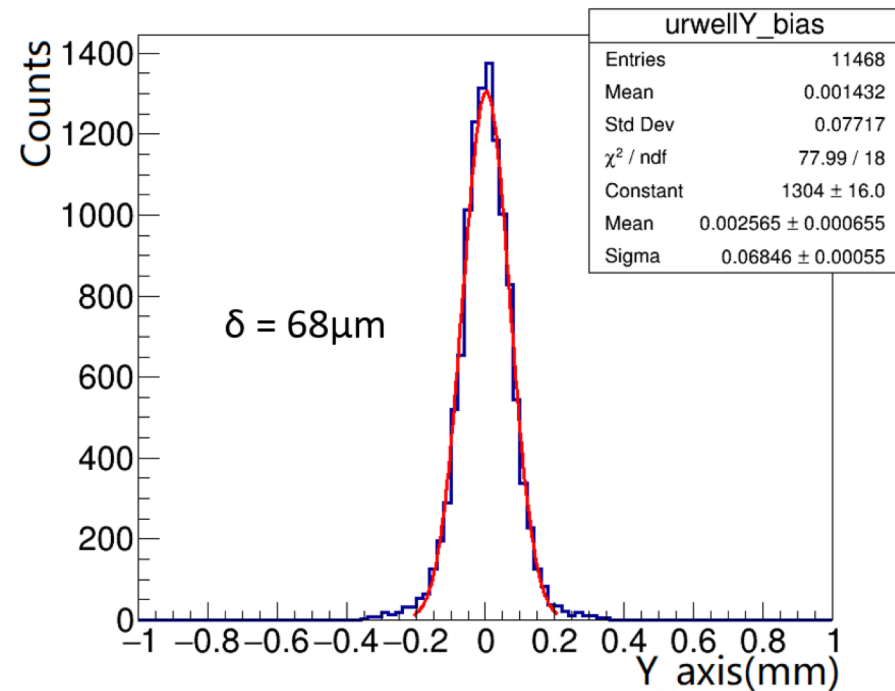
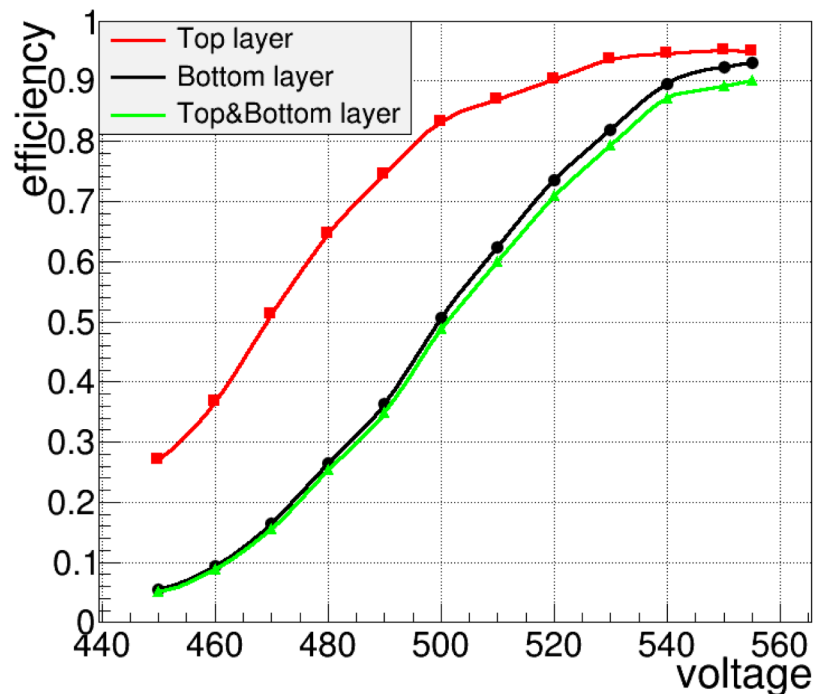


- Ar(70)/CO₂(30) gas mixture
- Source: 8keV copper X-rays
- Collimator: 5.5mm-diameter



Gas gain drops about **30%** @ **1MHz/cm²**

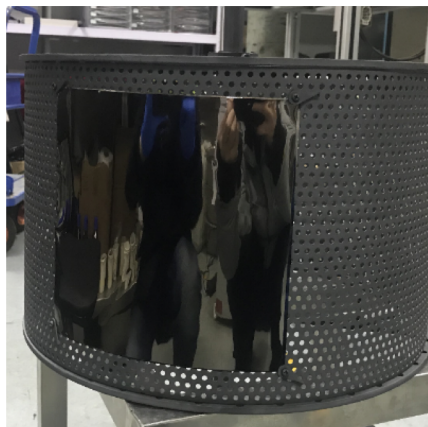
Efficiency and Spatial Resolution



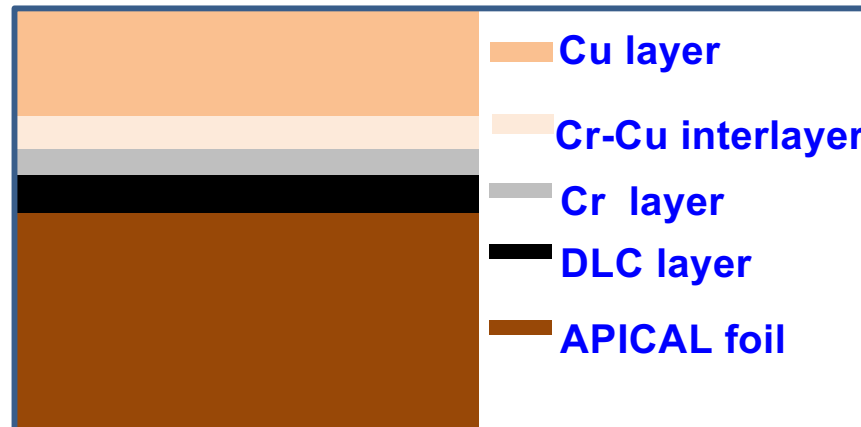
- Efficiency of top layer: $\sim 95\%$, bottom layer: $\sim 92\%$
- Signal induced on top layer ~ 2 times larger than that on bottom layer, strip layout needs to be optimized
- A position resolution better than $70\ \mu\text{m}$ is achieved in both dimensions

DLC+Cu Deposition

DLC coating
on substrate



Copper coating
on DLC



- Simplifying manufacturing process of resistive MPGDs and improving the quality.
- Allowing to create precise printed circuits on a DLC resistive electrode hence realizing complex functions
- opening ways for making new MPGD architectures

A critical element in making high-rate uRWELL structures

RD51 Common Project

- DLC based electrodes for future resistive MPGDs
- DLC+Cu is a central subject in this project

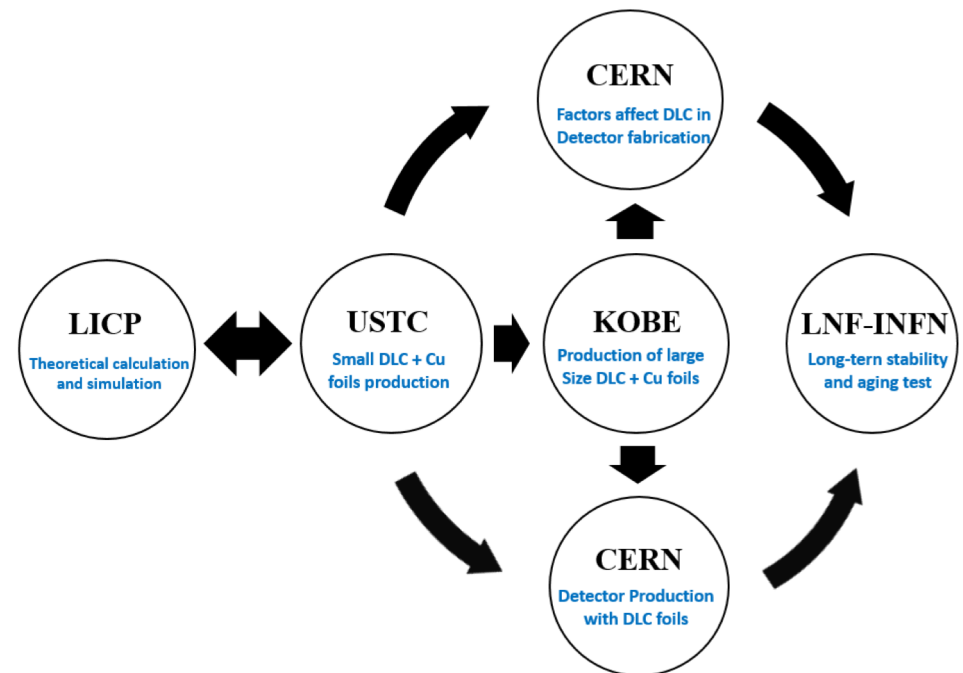
Title of project: *DLC based electrodes for future resistive MPGDs*

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USTC is leading this project.

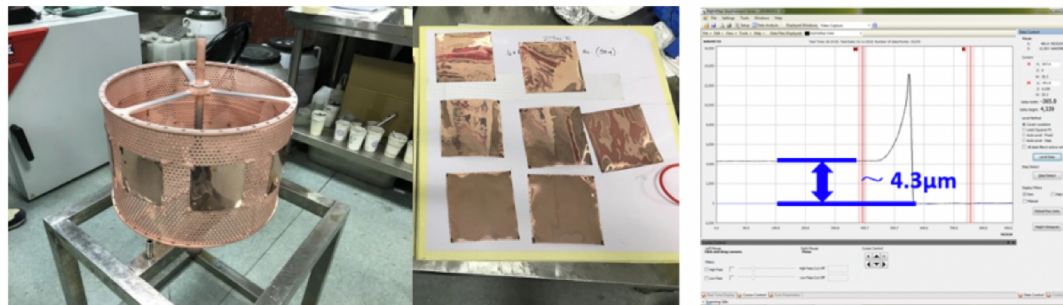
Big Progress on DLC+Cu

- Good adhesion has been achieved between DLC and copper by introducing a Cr transition layer.
- Cu coating thickness can be adjusted from 1-5 μm
- Many DLC+Cu samples have been produced for the MPGD community

Bending stress testing



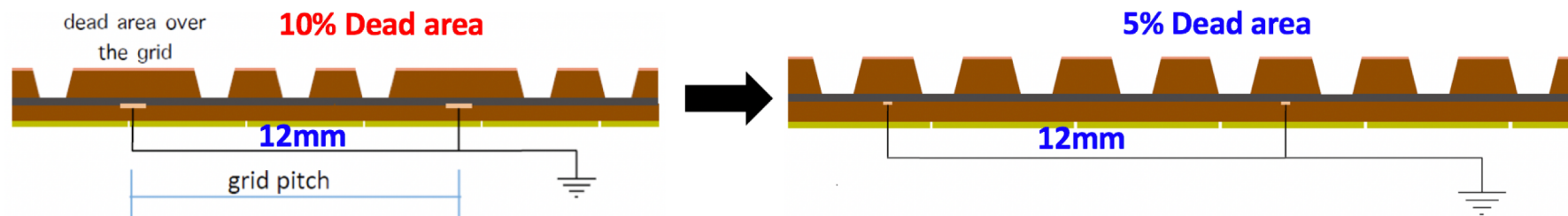
Cross-cutting testing



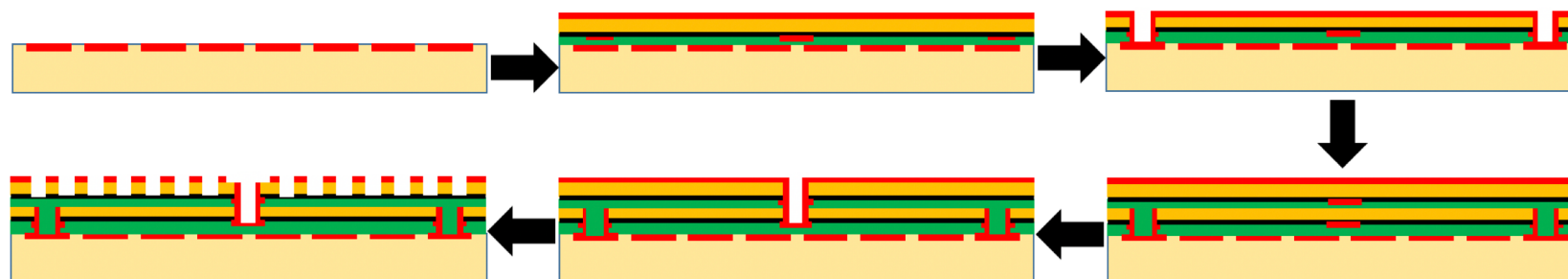
High-rate uRWELL Concepts

- Approach to high-rate: fast grounding
- Two structures being explored, which are only made possible with DLC+Cu

Single-DLC layer uRWELL with fast grounding lines



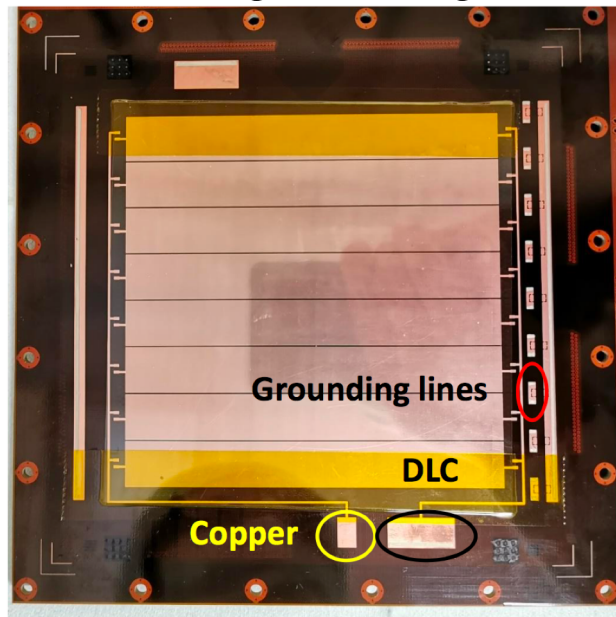
Double-DLC layer uRWELL with Sequential Build Up (SBU) technology : more promising for large area production



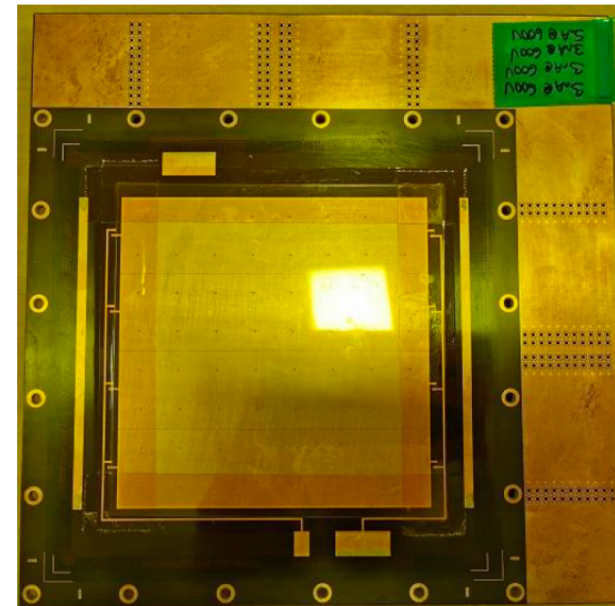
High-Rate uRWELL Prototypes

- Built a 10cm*10cm prototype with DLC+Cu for each of the two high-rate uRWELL schemes
- Observed signals with radioactive sources
- More testing is ongoing

Single-DLC layer uRWELL
with fast grounding lines



Double-DLC layer uRWELL
with SBU



Going for Large Size



A New sputtering system (Hauzer 850) is ready to make large-area DLC/DLC-Cu samples.

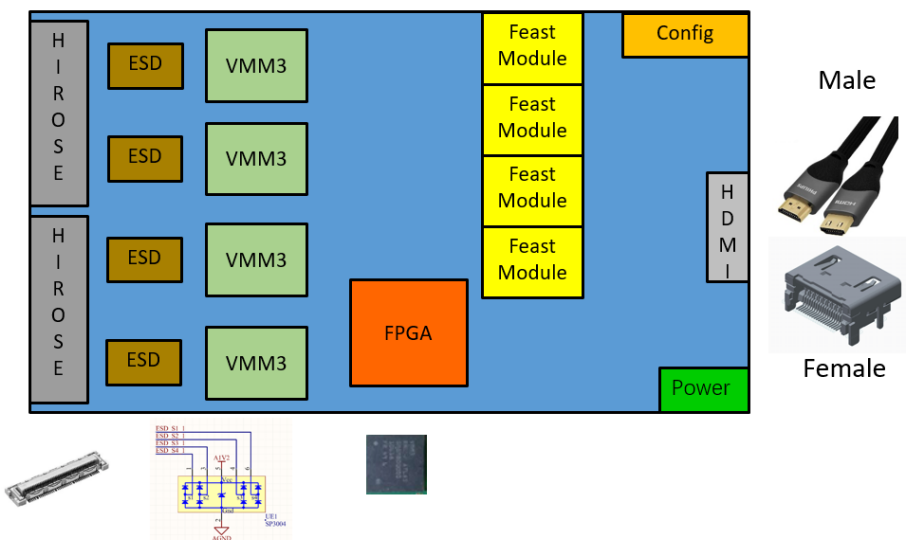
Chamber size: $\Phi 800\text{mm} \times 900\text{mm}$

**Best Sample size (up to): $500\text{mm} \times 500\text{mm}$ (Rigid substrate),
 $500\text{mm} \times 1900\text{mm}$ (Flexible substrate)**

A VMM-based Readout

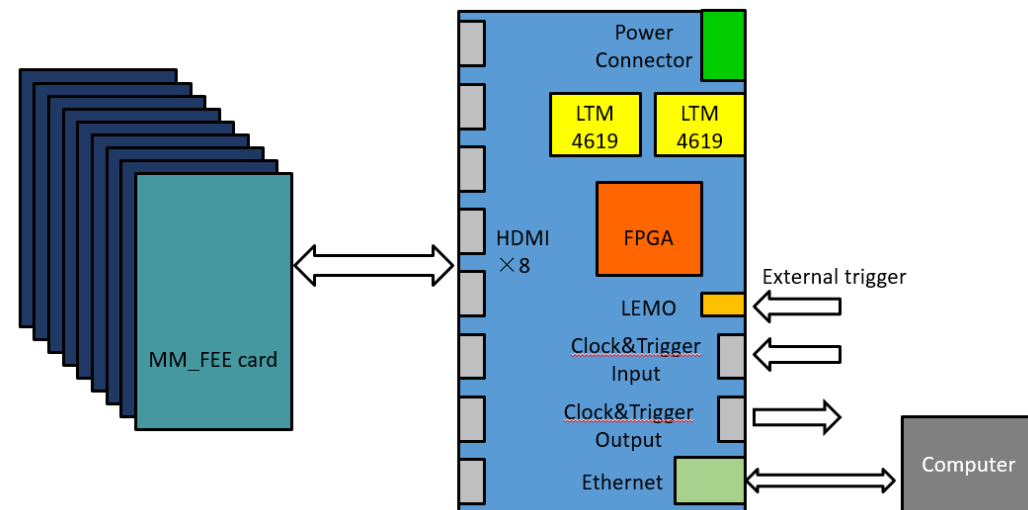
FEE card

- 4 VMM chips: 256 channels
- 64 4-channel ESDs (SP3004) for input protection
- HDMI (~340Mbps bandwidth) for output



DAQ board

- 8 HDMI (8 × 256 channels), scalable.
- Receive and fan out the clock and trigger signal and trigger signal
- Both auto-trigger and external trigger available.



Integration and Testing



FEE noise:

Standalone: $V_{p-p} \leq 4\text{mV}$, $V_{rms} \leq 800\mu\text{V}$

With detector: $V_{p-p} \leq 20\text{mV}$, $V_{rms} \leq 3\text{mV}$

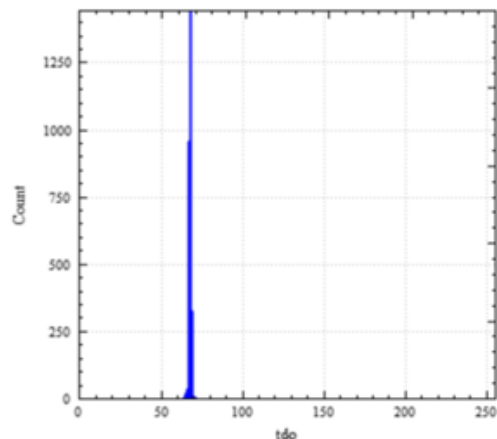


A Micromegas detector

Timing resolution:

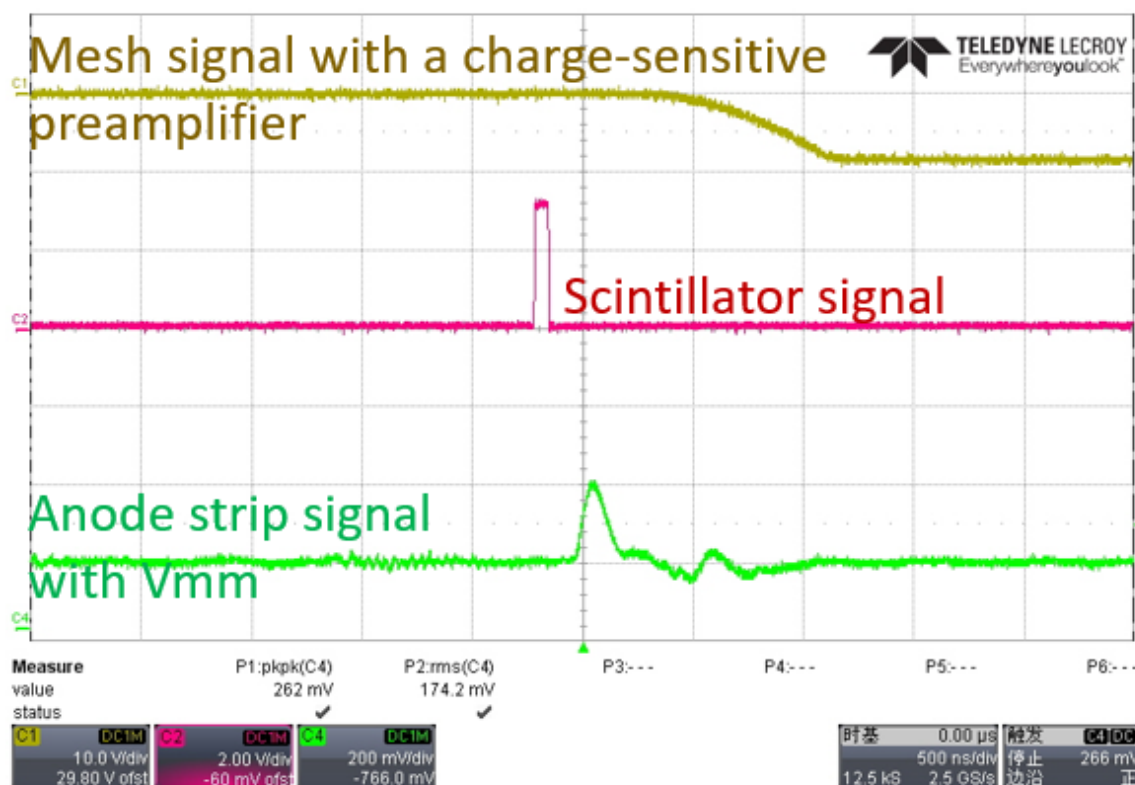
RMS = $\sim 0.5\text{ns}$

Channel tdo Distribution Graph 2

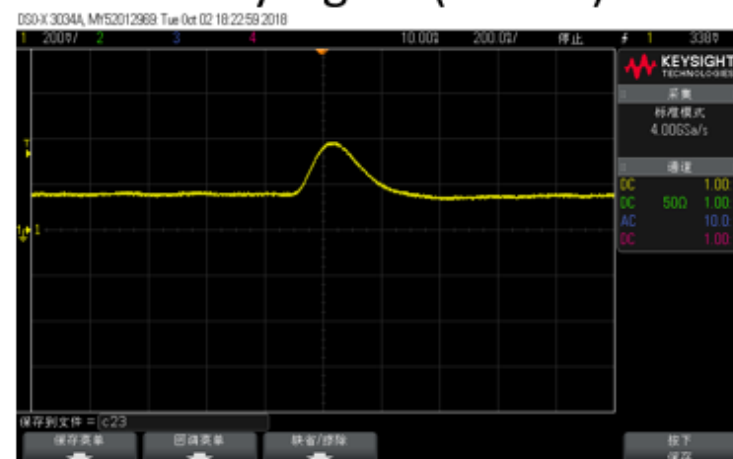


Signals with cosmic rays and X-rays

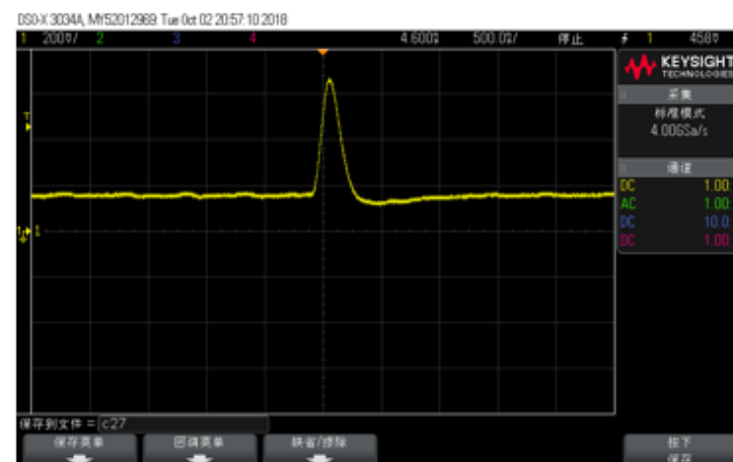
Testing with cosmic rays and 5.9keV x-rays



cosmic ray signal (anode)



X-ray signal (anode)



Summary

- uRWELL offers a promising alternative detector option for the SoLID tracker.
- A solid uRWELL R&D program in place at USTC
- Significant progress has been made on DLC resistive coating and high-rate uRWELL.
- VMM readout in development for high-rate MPGDs.